Filename: PMP8582 REV_C_bom.xls Date: 04/12/2013

PMP8582 REV_C BOM

COUNT	RefDes	Value	Description	Size	Part Number	Mfr
1	C1	2.2nF	Capacitor, Ceramic, 630V, X7R, 10%	1206	STD	TDK
1	C2	0.22 uF	Capacitor, Film, 250VAC, 20%	0.689 x 0.217	ECQU2A104xL	Panasonic
1	C3	47uF	Capacitor, Alum Electrolytic 16mm x 20mm, 400V, ±20%	16.00 mm Dia	EKXJ401ELL470ML20S	Nippon Chemi-Con
1	C6	470uF	Capacitor, Aluminum, 10mm x 16mm, 35V, 105C, 20%	10mm	EKZM350ELL471MJ16S	Nippon Chemi-Con
1	C7	1uF	Capacitor, Ceramic Chip, 100V, X7R, ±10%	1206	C3216X7R2A105K	TDK
1	C8	1500pF	CAP, CERM DISC Y1, 250Vac, 20%	.500 X .310	ECK-DNAxxxxMB	Panasonic
1	C9	27uF	Capacitor, Aluminum Electrolytic, 25V	4mm x 11mm	EEUFC1E270	Panasonic
1	C11	47nF	Capacitor, Ceramic, 50V, X7R, 10%	0603	STD	STD
1	C12	1000uF	Capacitor, Aluminum, 10mm x 16mm, 16V, 105C, 20%	10mm x 16mm	EKZM160ESS102MJ16S	Nippon Chemi-con
1	C13	10uF	Capacitor, Ceramic, 25V, X5R, 20%	1210	Std	TDK
1	C15	100nF	Capacitor, Ceramic, 50V, X7R, 10%	0603	STD	STD
1	C17	100nF	Capacitor, Ceramic Chip, 100V, ±10%	0805	C2012X7R2A104K	TDK
1	C18	22nF	Capacitor, Ceramic, Low Inductance, 50V, X7R, 10%	0603	Std	Std
1	C20	220pF	Capacitor, Ceramic, Low Inductance, 50V, X7R, 10%	0603	Std	Std
1	C21	330nF	Capacitor, Ceramic, 50V, X7R, 20%	0603	STD	TDK
2	C14 C16	100pF	Capacitor, Ceramic, 50V, COG, 10%	0603	STD	TDK
2	C19 C22	10nF	Capacitor, Ceramic, 50V, X7R, 10%	0603	STD	Std
3	C4-5 C10	3.3uF	Capacitor, Ceramic, 50V, X7R, 10%	1210	GRM32ER71H475KA88L	Murata
1	D1	MBRS3200	Diode, Schottky, 3-A, 200-V	SMB	MBRS3200T3G	ON Semi
1	D2	KBP06G	Diode, Bridge Rectifier, 1.5A, 600V	0.580 x 0.145 inch	KBP06G	Diodes
1	D3	MURA160T3	Diode, Rectifier, 1A, 600V	SMA	STD	ON Semiconductor
1	D4	MMBD1505A	Diode, Dual , 250mW, 200 V	SOT23	MMBD1505A	Farichild
1	D5	MBRA160	Diode, Schottky, 1-A, 60-V	SMA	MBRA160T3	ON Semi
1	D6	BAV199	Diode, Dual Series, 80V, 200mA	SOT23	BAV199	Infineon
1	D7	5.1V	Diode, Zener, 250-mW, 5.1-V	SOD123	MMSZ5231BT3G	On Semi
1	F1	2A	Fuse, TR5 Time Lag, 2A, 250V	0.335	370xxxx041	Littlefuse
1	HS1	592502	Heatsink, TO-220, Vertical-mount, 30*C/W	0.88 x 0.25 inch	592502 B 0 34 00	Thermalloy
1	L1	2.2uH	Inductor, SMT, 3.5A, 35milliohm	0.350 x 0.300 inch	DO1813H-222ML	Coilcraft
1	L2	20mH	Inductor, Common Mode, 0.5 A, 540 milliohm	12.5x18 mm	744822120	Wuerth
1	Q1	SPA03N60C3	MOSFET, N-ch, 650-V, 3.2-A, 1.4-Ohms	TO-220V	SPA03N60C3	Infineon
1	Q2	2N7002W	MOSFET, Nch, 60V, 115mA	SOT323 [SC70]	2N7002W	Diodes
1	R1	4.75	Resistor, Chip, 1/16W, 1%	0603	CRCW0603-xxxx-F	Vishay
1	R2	100k	Resistor, Metal -Mite, 2.5W, ±1%	{Size}	std	Std
1	R4	47	Resistor, Chip 1/4 watt, ± 5%	1206	STD	Std
1	R6	275V	Varistor, 275V	0.472 x 0.213 inch	SIOV-S10K275E2	Epcos
1	R10	2.21	Resistor, Chip, 1/16W, 1%	0603	STD	Std
1	R11	5.9k	Resistor, Chip, 1/16W, 1%	0603	STD	Std
1	R12	475	Resistor, Chip, 1/16W, 1%	0603	STD	Std
1	R13	127k	Resistor, Chip, 1/16W, 1%	0603	STD	Std
1	R14	10	Resistor, Chip, 1/16W, 1%	0603	STD	Std

1	R15	1.24k	Resistor, Chip, 1/16W, 1%	0603	STD	Std
1	R16	0.62	Resistor, Chip 1/4 watt, ±1%	1206	STD	STD
1	R17	22.6k	Resistor, Chip, 1/16W, 1%	0603	STD	Std
1	R18	2.21K	Resistor, Chip, 1/16W, 1%	0603	CRCW0603-xxxx-F	Vishay
1	R19	49.9	Resistor, Chip, 1/16W, 1%	0603	CRCW0603-xxxx-F	Vishay
1	R20	18.2k	Resistor, Chip, 1/16W, 1%	0603	CRCW0603-xxxx-F	Vishay
1	R21	105K	Resistor, Chip, 1/16W, 1%	0603	CRCW0603-xxxx-F	Vishay
1	R22	221k	Resistor, Chip, 1/16W, 1%	0603	CRCW0603-xxxx-F	Vishay
1	R23	1M	Resistor, Chip 1/4 watt, ±1%	1206	STD	STD
1	R24	4.99K	Resistor, Chip, 1/16W, 1%	0603	CRCW0603-xxxx-F	Vishay
1	R25	47.5k	Resistor, Chip, 1/16W, 1%	0603	STD	Std
1	R26	2.2M	Resistor, Chip, 1/16W, 1%	0603	STD	Std
1	R27	75k	Resistor, Chip, 1/16W, 1%	0603	STD	Std
2	R3 R7	1M	Resistor, Chip 1/4 watt, ± 5%	1206	STD	Std
2	R8-9	3.92M	Resistor, Chip 1/4 watt, ±1%	1206	STD	STD
1	RT1	10 Ohm	Thermistor, 8.5mm diam.	0.236 X 0.512 inch	B57153S0100M000	Epcos
1	T1	800uH	Transformer, 2 Prim, 3 Sec, Engineering Evaluation Only	1.050 x 1.050 inch	E25/13/7	EPCOS
8	TP1-3 TP5 TP7 TP9-11	5000	Test Point, Red, Thru Hole Color Keyed	0.100 x 0.100 inch	5000	Keystone
4	TP4 TP6 TP8 TP12	5001	Test Point, Black, Thru Hole Color Keyed	0.100 x 0.100 inch	5001	Keystone
1	U1	LM317	IC, Pos. Adj. Voltage Regulator, lout >1.5 A	TO-220	LM317KCT	TI
1	U2	UCC28600D	IC, Quasi-Resonant Flyback Green Mode Controller	SO8	UCC28600D	TI
1	U4	LMV431A	IC, Precision Adjustable Shunt Regulator	SOT23-3	LMV431AIMF	TI
1	U5	LM8364-20	Micropower Undervoltage Sensing Circuit	SOT23-5	LM8364BALMF20	TI
2	U3 U6	TCMT1107	IC, Photocoupler	MF4	TCMT1107	Vishay

Notes: 1. These assemblies are ESD sensitive, ESD precautions shall be observed.

2. These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

These assemblies must comply with workmanship standards IPC-A-610 Class 2.
Ref designators marked with an asterisk ('**') cannot be substituted. All other components can be substituted with equivalent MFG's components.

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